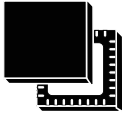


## STSAFE-TPM trusted platform module 2.0 with a SPI or I<sup>2</sup>C interface



UFQFPN32 (5 × 5 × 0.55 mm)



### Product status

ST33KTPM2X

## Features

### TPM features

- Flash-memory-based trusted platform module (*TPM*)
- Compliant with Trusted Computing Group (*TCG*) trusted platform module (*TPM*) Library specifications 2.0, revision 1.59 errata version 1.4 and *TCG* PC Client Platform *TPM* Profile (*PTP*) for *TPM* 2.0 Version 1.05
- Fault-tolerant firmware loader that keeps the *TPM* fully functional when the loading process is interrupted (self-recovery)
- SP800-193 compliant for protection, detection and recovery requirements
- Targeted certifications:
  - Common Criteria EAL4+ in compliance with the *TPM* 2.0 protection profile (augmented with AVA\_VAN.5, resistant to high-potential attacks)
  - FIPS 140-3
  - *TCG* certification
- SPI communication bus running at up to 66 MHz
- I<sup>2</sup>C communication bus running at up to 1 Mb/s

### Hardware features

- Highly reliable flash memory with error correction code
- Extended temperature range: -40 °C to 105 °C
- Electrostatic discharge (ESD) protection up to 4 kV (HBM)
- 1.8 V or 3.3 V supply voltage range

### Security features

- Active shield
- Monitoring of environmental parameters
- Hardware and software protection against fault injection and side channel attacks
- *FIPS* SP800-90A and AIS20-compliant deterministic random-bit generator (*DRBG*)
- *FIPS* SP800-90B and AIS31-compliant true random-number generator (*TRNG*)
- Cryptographic algorithms:
  - RSA key generation (1024, 2048, 3072 and 4096 bits)
  - RSA signature (RSASSA-PSS, RSASSA-PKCS1v1\_5)
  - RSA encryption (RSAES-OAEP, RSAESPKCS1-v1\_5)
  - SHA-1, SHA-2 (256 and 384 bits), SHA-3 (256 and 384 bits)
  - HMAC SHA-1, SHA-2 and SHA-3
  - AES-128, 192 and 256 bits
  - ECC (NIST P-256, P-384 curves): key generation, ECDH and ECDSA, ECSchnorr
  - ECDAA (BN-256 curve)
- Device provided with 3 endorsement keys (*EK*) and *EK* certificates (RSA2048, ECC NIST P\_256 and ECC NIST P\_384)
- Device provisioned with three 2048-bit RSA key pairs to reduce the *TPM* provisioning time

**Product's targeted compliance**

- Compliant with Microsoft® Windows® 10 and 11
- Compliant with Linux® drivers
- Compliant with Intel® vPro® technology
- Compliant with TCG test suite for TPM 2.0
- Compliant with the open-source TCG TPM 2.0 TSS implementation

## 1 Description

The STSAFE-TPM (trusted platform module) family of products offers a broad portfolio of standardized solutions for embedded, PC, mobile, and computing applications.

It includes turnkey products compliant with the Trusted Computing Group (TCG) standards that provide services to protect the confidentiality, integrity, and authenticity of information and devices.

The STSAFE-TPM devices are easy to integrate thanks to the variety of supported interfaces and the availability of TPM ecosystem software solutions.

The STSAFE-TPM devices target Common Criteria, TCG, and FIPS certifications.

The **ST33KTPM2X** offers a slave serial peripheral interface (SPI) or a target I<sup>2</sup>C interface, both compliant with the TCG *PC Client TPM Profile* specifications.

It offers resilience services during the TPM firmware upgrade process, and self-recovery of TPM firmware and critical data upon failure detection.

The **ST33KTPM2X** operates in the -40 °C to 105 °C extended temperature range.

The device is offered in the UFQFPN32 ECOPACK2 package. ECOPACK is an ST trademark.



## 2 UFQFPN32 pin and signal description

The figure below gives the pinout of the UFQFPN32 package in which the devices are delivered. The table describes the associated signals.

Figure 1. UFQFPN32 pinout

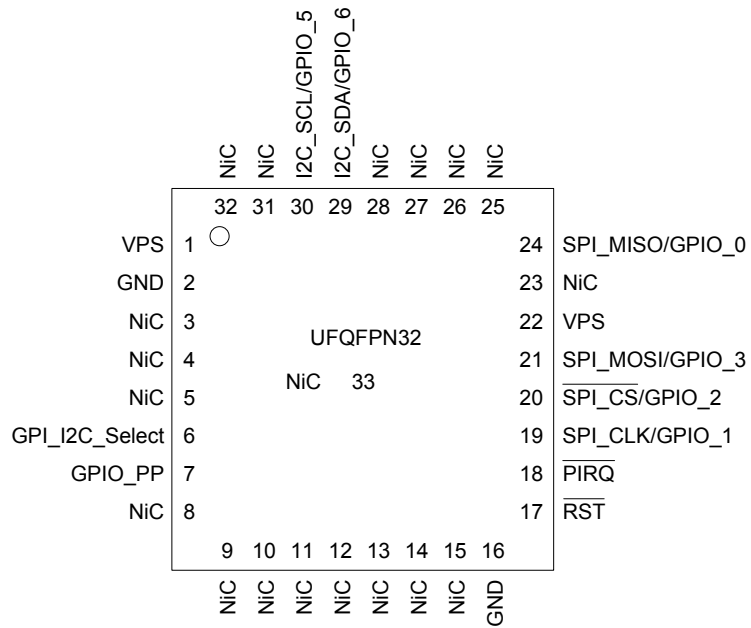


Table 1. Pin descriptions

Signal	Type	Description
VPS	Input	<b>Power supply.</b> This pin must be connected to 1.8 V or 3.3 V DC power rail supplied by the motherboard.
GND	Input	<b>Ground,</b> has to be connected to the main motherboard ground.
$\overline{\text{RST}}$	Input	<b>Reset,</b> active low, used to re-initialize the device. Must not be unconnected. External pull-up resistor required if it cannot be driven.
SPI_MISO	Output	<b>SPI Master Input, Slave Output</b> (output from slave)
SPI_MOSI	Input	<b>SPI Master Output, Slave Input</b> (output from master)
SPI_CLK	Input	<b>SPI Serial Clock</b> (output from master)
$\overline{\text{SPI\_CS}}$	Input	<b>SPI Chip (or Slave) Select,</b> internal pull-up (active low; output from master)
$\overline{\text{PIRQ}}$	Output	<b>IRQ,</b> active low, open drain, used by the TPM to generate an interrupt
GPIO_PP	Input	<b>Physical Presence,</b> active high, internal pull-down. Used to indicate Physical Presence to the TPM. The GPIO function could be modified by activating the GPIOs mapped with the NV storage index feature.
GPI_I2C_Select	Input	This pin must be connected to an external pull-down resistor to activate the I <sup>2</sup> C protocol during product boot time. It can remain unconnected for the SPI protocol. This pin is internal pull-up by default and becomes internal floating after I <sup>2</sup> C activation.
NiC	-	<b>Not internally connected:</b> not connected to the die. May be left unconnected but no impact on TPM if connected.
GPIO_X	Input/Output	The GPIO function could be modified by activating the GPIOs mapped with the NV storage index feature. GPIO availability is dependent of bus interface (for example, GPIO_5 and GPIO_6 are available with the SPI interface activated).
I2C_SDA	Input/Output	Bidirectional I <sup>2</sup> C serial data (open drain without a weak pull-up resistor).
I2C_SCL	Input	Input I <sup>2</sup> C serial clock (open drain without a weak pull-up resistor).

*Note:* The UFQFPN32 package has a central pad (PIN33) on the bottom, which is not connected to the die. This pin does not impact the TPM, be it connected or not.

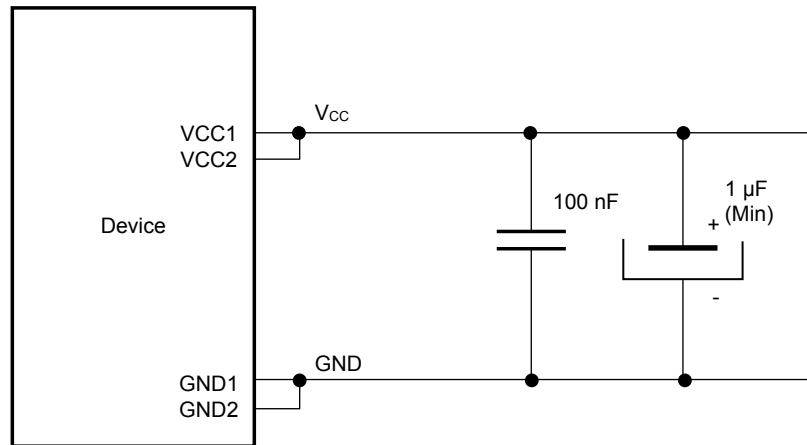
### 3 Electrical integration guidance

This section gives some guidance on how to integrate the ST33KTPM2X device in an application.

#### 3.1 Recommended power supply filtering

The power supply of the device should be filtered using the circuit shown in the figure below.

Figure 2. Recommended filtering capacitors on V<sub>CC</sub>



DT64224V1

Table 2. V<sub>CC</sub> rising slope

Data based on design simulation and/or characterization results, not tested in production.

Symbol	Parameter	Min.	Typ.	Max.	Unit
S <sub>VCC</sub>	V <sub>CC</sub> rising slope	2	-	2 · 10 <sup>3</sup>	V/ms

*Note:* Measurement must be done between 1.36 V and 1.62 V. If V<sub>CC</sub> rising slope requirement is unreachable for the concerned platform or if there is any other noisy environment at boot, a "power-on reset and warm reset sequence" must be run.

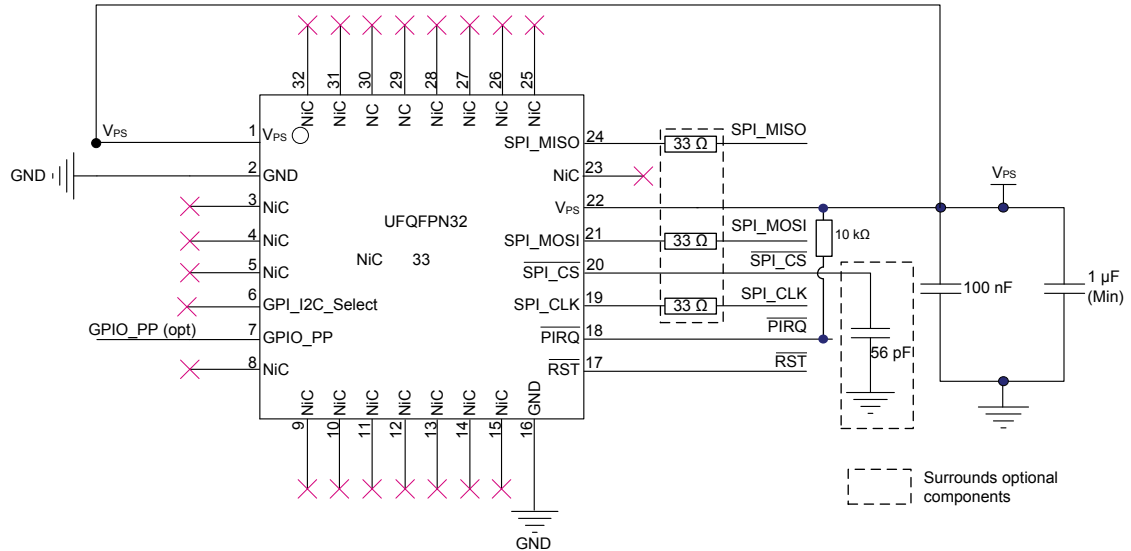
#### 3.2 SPI\_CS optional filtering

Recommendation for SPI\_CS integration: It is mandatory that SPI\_CLK is at the low logic level when the falling edge occurs on the SPI\_CS signal. An external capacitance of 56 pF is recommended on SPI\_CS for that purpose. This capacitor might not be required depending on the intrinsic line capacitance, the SPI bus frequency, or both.

### 3.3 Device integration for SPI communication

The figure below shows the typical hardware implementation of the ST33KTPM2X device for SPI communication.

**Figure 3. Typical hardware implementation for SPI communication (UFQFPN32 package)**



DT68866V1

**Note:** The use of a low-value resistor (typically 33  $\Omega$ ) on SPI\_MISO, SPI\_MOSI and SPI\_CLK can be recommended for line adaptation when the signals are affected by parasite spikes. Its use is mandatory to avoid disturbance of the ramp-up and ramp-down signals.

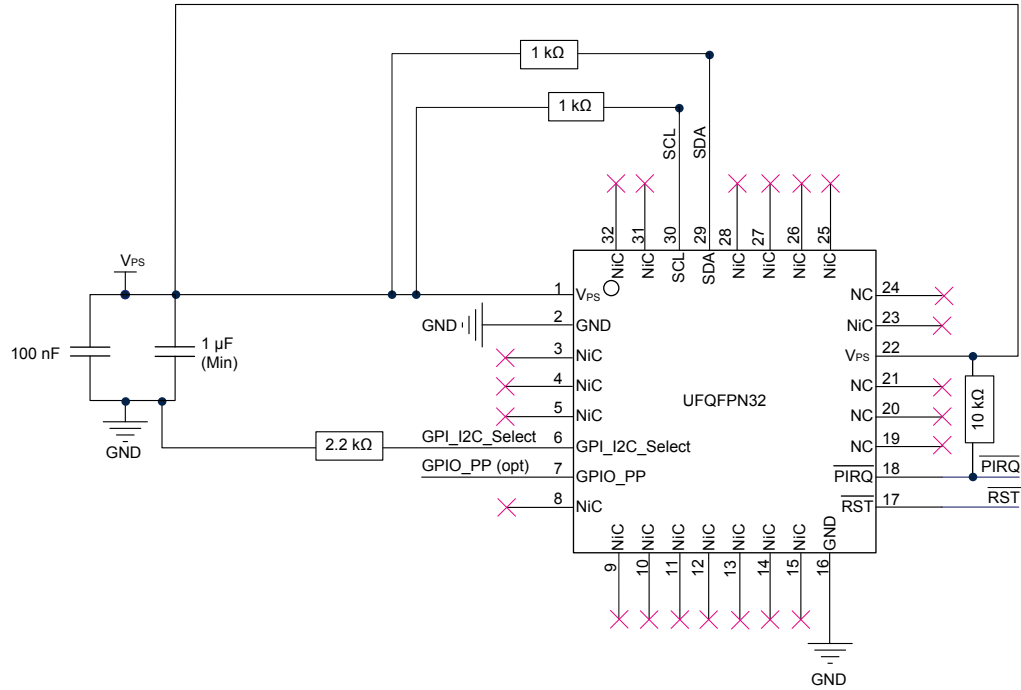
**Note:** The capacitor on  $\overline{\text{SPI\_CS}}$  is optional (see Section 3.2: [SPI\\_CS optional filtering](#)).

**Note:** The pull-up resistor on the PIRQ line is mandatory to optimize the power consumption in standby mode.

### 3.4 Device integration for I<sup>2</sup>C communication

The figure below shows the typical hardware implementation of the ST33KTPM2X device for I<sup>2</sup>C communication.

Figure 4. Typical hardware implementation for I<sup>2</sup>C communication (UFQFPN32 package)



DT68667V2

**Note:** The pull-up resistor on the PIRQ line is mandatory to optimize the power consumption in standby mode.



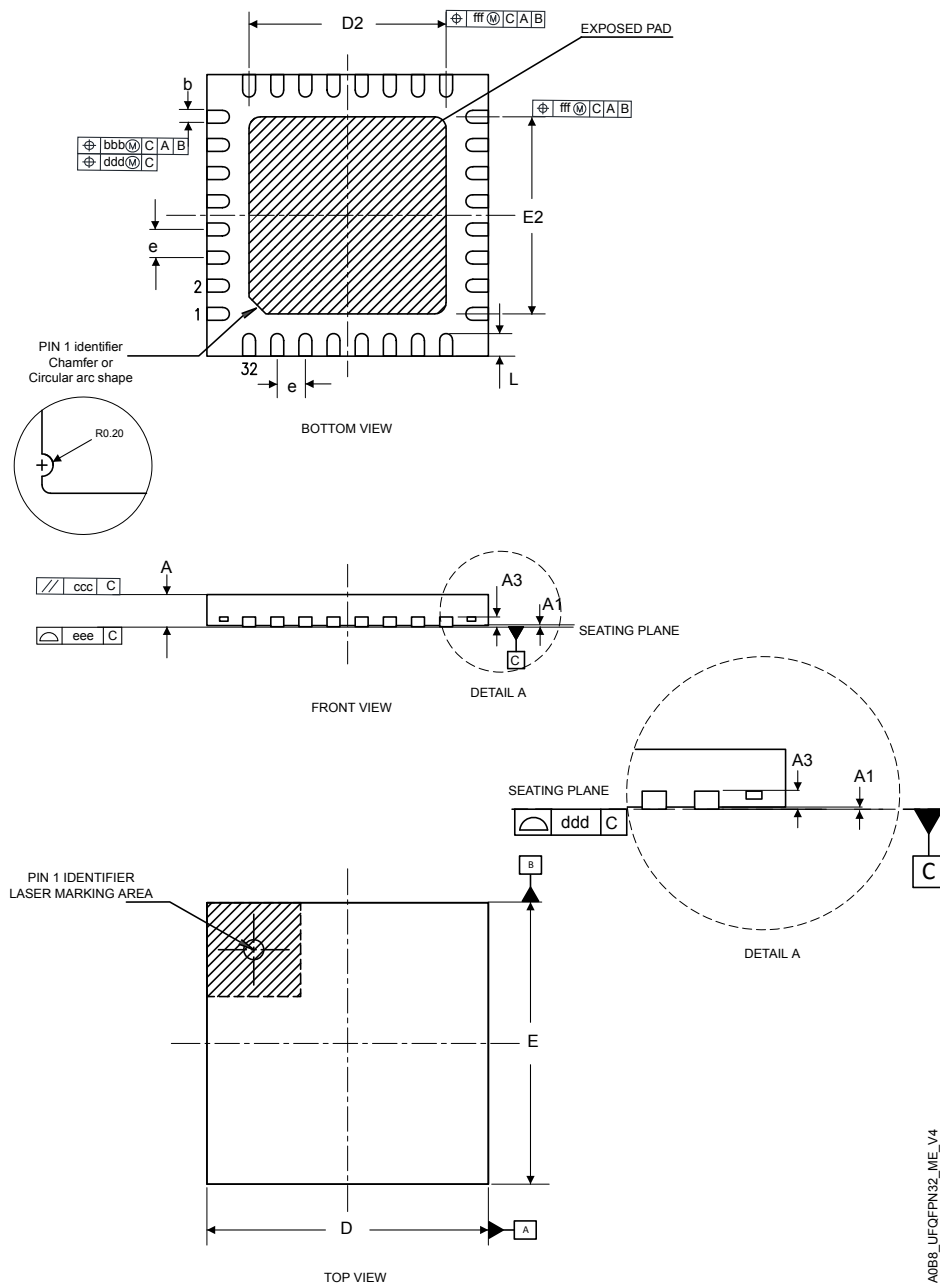
## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 UFQFPN32 package information

This UFQFPN is a 32 pins, 5x5 mm, 0.5 mm pitch ultra thin fine pitch quad flat package.

Figure 5. UFQFPN32 - Outline



A0B8\_UFQFPN32\_ME\_V4

1. Drawing is not to scale.
2. All leads/pads should also be soldered to the PCB to improve the lead/pad solder joint life.

- There is an exposed die pad on the underside of the UFQFPN package. It is recommended to connect and solder this backside pad to PCB ground.

**Table 3. UFQFPN32 - Mechanical data**

Symbol	millimeters <sup>(1)</sup>			inches <sup>(2)</sup>		
	Min	Typ	Max	Min	Typ	Max
A <sup>(3)(4)</sup>	0.50	0.55	0.60	0.0197	0.0217	0.0236
A1 <sup>(5)</sup>	0.00	-	0.05	0.000	-	0.0020
A3 <sup>(6)</sup>	-	0.15	-	-	0.0060	-
b <sup>(7)</sup>	0.18	0.25	0.30	0.0071	0.010	0.0118
D <sup>(8)(9)</sup>	5.00 BSC			0.1969 BSC		
D2	3.50	3.60	3.70	0.139	0.143	0.147
E <sup>(8)(9)</sup>	5.00 BSC			0.1969 BSC		
E2	3.50	3.60	3.70	0.139	0.143	0.147
e <sup>(9)</sup>	-	0.50	-	-	0.02	-
N <sup>(10)</sup>				32		
K	0.15	-	-	0.006	-	-
L	0.30	-	0.50	0.0119	-	0.0199
R	0.09	-	-	0.004	-	-

- All dimensions are in millimetres. Dimensioning and tolerancing schemes are conform to ASME Y14.5M-2018 except European.
- Values in inches are converted from mm and rounded to 4 decimal digits.
- UFQFPN stands for Ultra thin Fine pitch Quad Flat Package No lead:  $A \leq 0.60\text{mm}$  / Fine pitch  $e \leq 1.00\text{mm}$ .
- The profile height, A, is the distance from the seating plane to the highest point on the package. It is measured perpendicular to the seating plane.
- A1 is the vertical distance from the bottom surface of the plastic body to the nearest metallized package feature.
- A3 is the distance from the seating plane to the upper surface of the terminals.
- Dimension b applies to metallized terminal. If the terminal has the optional radius on the other end of the terminal, the dimension b must not be measured in that radius area.
- Dimensions D and E do not include mold protrusion, not to exceed 0,15mm.
- BSC stands for BASIC dimensions. It corresponds to the nominal value and has no tolerance. For tolerances refer to Table 4
- N represents the total number of terminals.

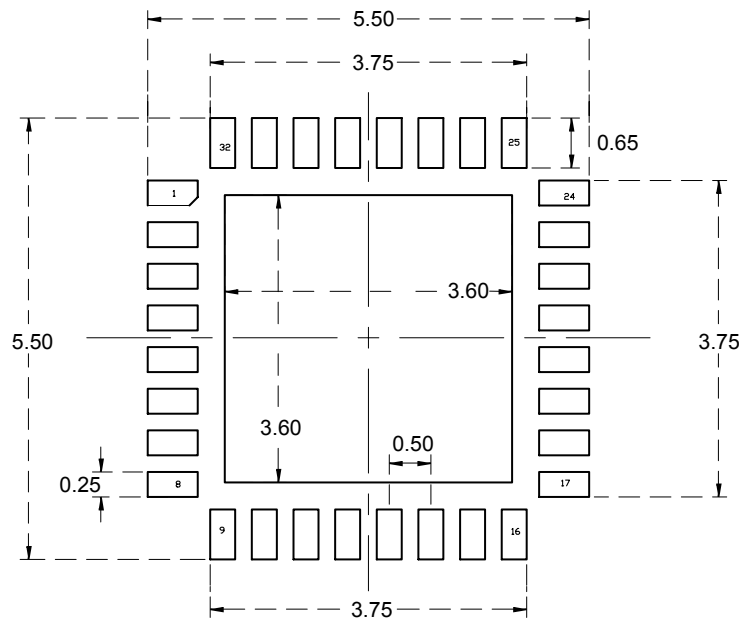
**Table 4. Tolerance of form and position**

Symbol <sup>(1)</sup>	Tolerance of form and position <sup>(2)</sup>	Tolerance of form and position <sup>(3)</sup>
	In millimeters	In inches
aaa	0.15	0.006
bbb	0.10	0.004
ccc	0.10	0.004
ddd	0.05	0.002
eee	0.10	0.004
fff	0.10	0.004

- For the tolerance of form and position definitions see Table 5.
- All dimensions are in millimetres. Dimensioning and tolerancing schemes are conform to ASME Y14.5M-2018 except European.
- Values in inches are converted from mm and rounded to 4 decimal digits.

**Table 5. Tolerance of form and position symbol definition**

Symbol	Definition
aaa	The bilateral profile tolerance that controls the position of the plastic body sides. The centres of the profile zones are defined by the basic dimensions D and E.
bbb	The tolerance that controls the position of the terminals with respect to Datums A and B. The centre of the tolerance zone for each terminal is defined by basic dimension e as related to datums A and B.
ccc	The tolerance located parallel to the seating plane in which the top surface of the package must be located.
ddd	The tolerance that controls the position of the terminals to each other. The centres of the profile zones are defined by basic dimension e.
eee	The unilateral tolerance located above the seating plane wherein the bottom surface of all terminals must be located = coplanarity
fff	The tolerance that controls the position of the exposed metal heat feature. The centre of the tolerance zone is the data defined by the centrelines of the package body

**Figure 6. UFQFPN32 - Footprint example**


1. Dimensions are expressed in millimeters.

## 4.2 Thermal characteristics of packages

The table below provides the thermal characteristics of the UFQFPN32 package.

**Table 6. Thermal characteristics**

Parameter		Symbol	Value
Recommended operating temperature range	Ambient temperature	$T_A$	-40 to 105 °C
	Case temperature	$T_C$	-
	Junction temperature	$T_J$	-43 to 108 °C
Absolute maximum junction temperature		-	125 °C
Maximum power dissipation		-	66 mW
Theta-JA, -JB and -JC	Junction to ambient thermal resistance	$\theta_{JA}^{(1)}$	35 °C/W
	Junction to case thermal resistance	$\theta_{JC}$	5 °C/W
	Junction to board thermal resistance	$\theta_{JB}$	20 °C/W

1. According to JESD51-2 (still air condition).

## 5 Delivery packing

Surface-mount packages can be supplied with tape and reel packing. The reels have a 13" typical diameter. Reels are in plastic, either anti-static or conductive, with a black conductive cavity tape. The cover tape is transparent anti-static or conductive.

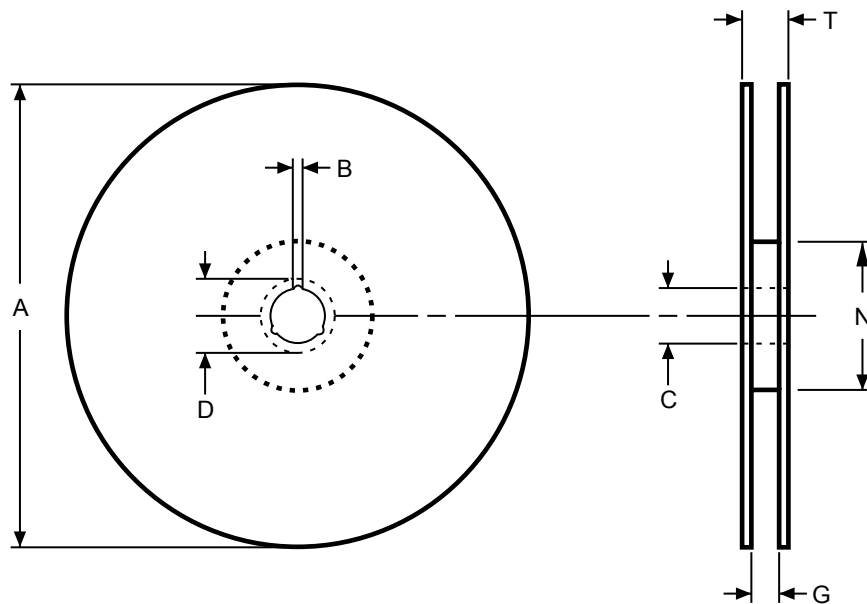
The devices are positioned in the cavities with the identifying pin (normally Pin "1") on the same side as the sprocket holes in the tape.

The STMicroelectronics tape and reel specifications are compliant with the EIA 481-A standard specification.

**Table 7. Packages on tape and reel**

Package	Description	Tape width	Tape pitch	Reel diameter	Quantity per reel
UFQFPN32	Ultra thin fine pitch quad flat pack no-lead package	12 mm	8 mm	13 in.	3000

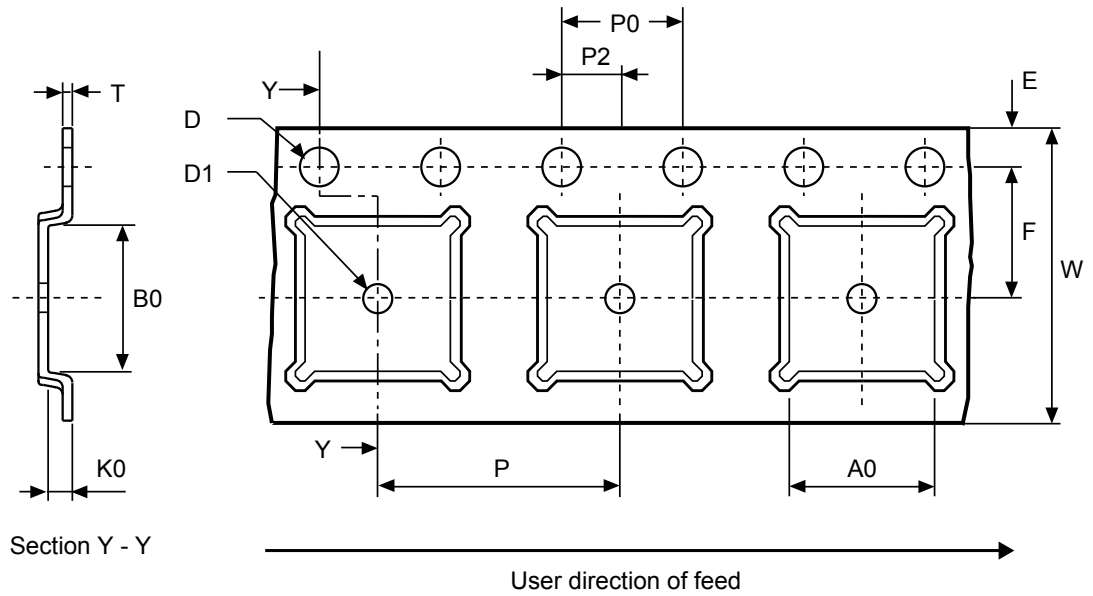
**Figure 7. Reel diagram**



**Table 8. Reel dimensions**

Reel size	Tape width	A Max.	B Min.	C	D Min.	G Max.	N Min.	T Max.	Unit
13"	12	330	1.5	13 ±0.2	20.2	12.6	100	18.4	mm

Figure 8. UFQFPN32 - Embossed carrier tape



1. Drawing is not to scale.

Figure 9. UFQFPN32 - Chip orientation in the embossed carrier tape

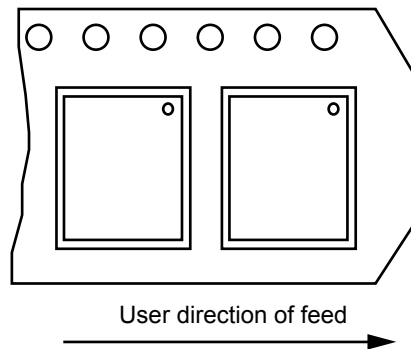


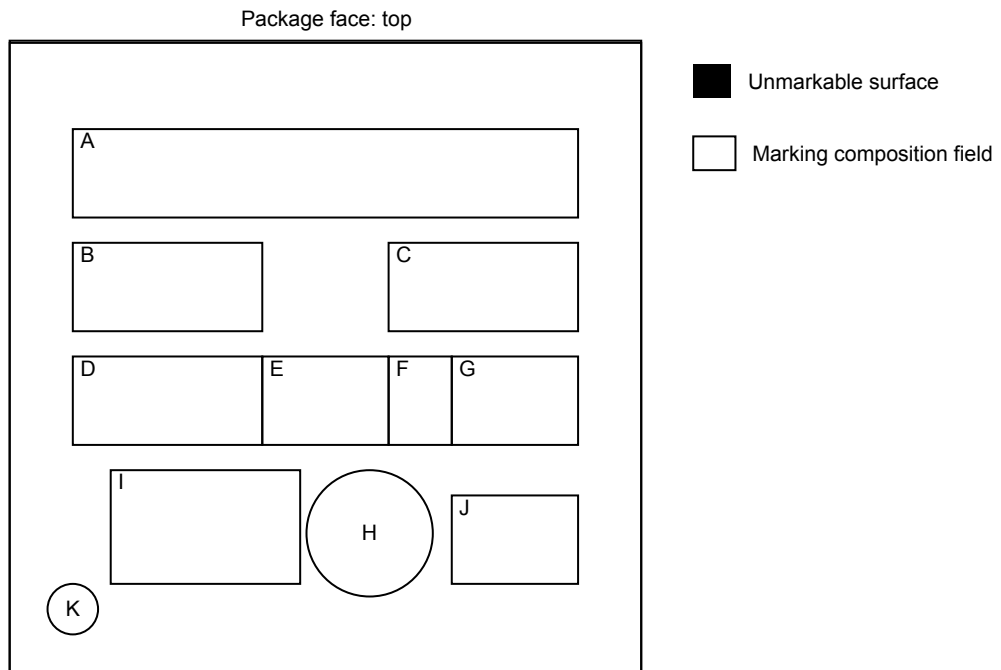
Table 9. UFQFPN32 - Carrier tape dimensions

Package	A0	B0	K0	D1 Min.	P	P2	D	P0	E	F	W	T Max.	Unit
UFQFPN 5x5	5.3 ±0.1	5.3 ±0.1	0.75 ±0.1	1.5	8 ±0.1	2 ±0.05	1.55 ±0.05	4 ±0.1	1.75 ±0.1	5.5 ±0.1	12 ±0.3	0.3 ±0.05	mm

## 6 UFQFPN32 package marking information

Parts marked as E or ES (for engineering sample) are not yet qualified and therefore not approved for use in production. ST is not responsible for any consequences resulting from such use. In no event will ST be liable for the customer using any of these engineering samples in production. ST's Quality department must be contacted prior to any decision to use these engineering samples to run a qualification activity.

**Figure 10. UFQFPN32 - Standard marking example**



Legend:

- |  |                                      |
|--|--------------------------------------|
| A: Marking area – Up to 8 digits                   | G: Assembly week (WW)                |
| B: Marking area – 3 digits                         | H: Second level interconnect         |
| C: BE sequence (LLL)                               | I: Standard STMicroelectronics logo  |
| D: Country of origin (3 characters allowed (max.)) | J: Diffusion traceability plant (WX) |
| E: Assembly plant (PP)                             | K: Dot <sup>(1)</sup>                |
| F: Assembly year (Y)                               |                                      |

1. The dot on the back side indicates the pin 1 location.

## 7 Ordering information

**Table 10. Ordering information**

Ordering code	Product line	Factory firmware version	Package	Minimum ordering quantity	Marking (area A)	Marking (area B)
ST33KTPM2X32DKG9	ST33KTPM2X	0x00.09.01.01 (09.257)	UFQFPN32	3000	KTPM	KG9

**Note:** *The ST33KTPM2X supports exactly the same features as product ST33KTPM2XI2C and both support the same firmware images. The ST33KTPM2XI2C is rebranded to ST33KTPM2X as both products support both the SPI and I2C interfaces.*

*The ST33KTPM2X and ST33KTPM2XI2C products do not share the same production sites.*



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## 8 Support and information

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Additional information regarding ST TPM devices can be obtained from the [www.st.com](http://www.st.com) website.

For any specific support information you can contact STMicroelectronics through the following e-mail:  
*[TPMsupport@list.st.com](mailto:TPMsupport@list.st.com)*.

STMicroelectronics has put in place a Product Security Incident Response Team (ST PSIRT). We encourage you to report any potential security vulnerability that you might suspect in our products through the ST PSIRT web page: <https://www.st.com/psirt>.

## Appendix A Referenced documents

The following materials are to be used in conjunction with or are referenced by this document.

[TPM 2.0 P1 r159]	TPM Library, Part 1, Architecture, Family 2.0, rev 1.59, TCG
[TPM 2.0 P2 r159]	TPM Library, Part 2, Structures, Family 2.0, rev 1.59, TCG
[TPM 2.0 P3 r159]	TPM Library, Part 3, Commands, Family 2.0, rev 1.59, TCG
[TPM 2.0 P4 r159]	TPM Library, Part 4, Supporting routines, Family 2.0, rev 1.59, TCG
[TPM 2.0 rev159 Err 1.4]	Errata Version 1.4 for Trusted Platform Module Library Family 2.0 Revision 1.59, TCG
[PTP 2.0 r1.05]	TCG PC Client Platform TPM Profile (PTP) for TPM 2.0 Version 1.05 Revision 14, TCG
[PTP 2.0 errata]	Errata version 1.0 for PC Client Platform TPM Profile (PTP) for TPM 2.0 Version 1.05 Revision 0.14, TCG
[PKCS#1]	PKCS#1: v2.1 RSA Cryptography Standard, RSA Laboratories
[AN2639]	Application note, Soldering recommendations and package information for Lead-free ECOPACK microcontrollers, STMicroelectronics
[TCG EK Cre Profile TPM 2.3]	TCG EK credential profile for TPM Family 2.0 Level 0. Specification Version 2.3 Revision 2, 23 July 2020, TCG.
[TPM 2.0 PP]	TCG Protection Profile for PC Client Specific TPM 2.0 Library Revision 1.59; Version 1.3
[SP800-90B]	Recommendation for the entropy sources used for random bit generation, January 2018, NIST
[SP800-90Ar1]	Recommendation for random number generation using deterministic random bit generators, June 2015, NIST

## Revision history

**Table 11. Document revision history**

Date	Revision	Changes
15-Dec-2023	1	Initial release.
23-Apr-2024	2	Updated: <ul style="list-style-type: none"><li>Section 7: Ordering information</li></ul>

## Glossary

<b>3D</b> Three-dimensional	<b>NIST</b> National Institute of Standards and Technology
<b>AES</b> Advanced encryption standard	<b>NV</b> Nonvolatile
<b>CA</b> Certification Authority	<b>PKCS</b> Public key cryptographic standards
<b>CC</b> Common Criteria	<b>PSS</b> Probabilistic signature scheme
<b>CML</b> Code memory loader	<b>RNG</b> Random number generator
<b>CRT</b> Chinese remainder theorem	<b>RSA</b> Public-key cryptosystem (created by Ron Rivest, Adi Shamir and Leonard Adleman)
<b>DES</b> Data encryption standard	<b>RSAES</b> Rivest Shamir Adelman encryption/decryption scheme
<b>DRBG</b> Deterministic random bit generator	<b>RSASSA</b> Rivest Shamir Adelman signature scheme with appendix
<b>DXE</b> Driver execution environment	<b>SHA</b> Secure Hash algorithm
<b>EC</b> Elliptic curve	<b>SPI</b> Serial peripheral interface
<b>ECC</b> Elliptic curve cryptography	<b>TCG</b> Trusted Computing Group®
<b>ECDA</b> Elliptic curve direct anonymous attestation	<b>TDES</b> Triple DES cryptographic algorithm
<b>ECDAA</b> Elliptic curve direct anonymous attestation (algorithm)	<b>TPM</b> Trusted platform module
<b>ECDH</b> Elliptic curve Diffie–Hellman	<b>TRNG</b> True random number generator
<b>ECDSA</b> Elliptic curve digital signature algorithm	<b>TSS</b> TPM software stack
<b>EK</b> Endorsement key	
<b>ESD</b> Electrostatic discharge	
<b>FIPS</b> Federal Information Processing Standards	
<b>FU</b> Field upgrade	
<b>GPIO</b> General purpose input/output	
<b>HBM</b> Human body model	
<b>HMAC</b> Hash-based message authentication code or keyed-hash message authentication code	
<b>I<sup>2</sup>C</b> Inter-integrated circuit	
<b>MCU</b> Microcontroller unit	

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Figure 10.	UFQFPN32 - Standard marking example . . . . .	15

**IMPORTANT NOTICE – READ CAREFULLY**

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